505771431 11/13/2019

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HYUN KWANG SHIN	11/07/2019

RECEIVING PARTY DATA

Name:	MAGNACHIP SEMICONDUCTOR, LTD.	
Street Address:	215, DAESIN-RO, HEUNGDEOK-GU, CHUNGCHEONGBUK-DO	
City:	CHEONGJU-SI	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	28429	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16682439

CORRESPONDENCE DATA

Fax Number: (202)315-3758

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 202-429-0020 Email: pto@nsiplaw.com

Correspondent Name: NSIP LAW

Address Line 1: P.O. BOX 65745

Address Line 4: WASHINGTON, D.C. 20035

ATTORNEY DOCKET NUMBER:	023103.0211
NAME OF SUBMITTER:	WALE T. GODO
SIGNATURE:	/Wale T. Godo/
DATE SIGNED:	11/13/2019

Total Attachments: 2

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PATENT 505771431 REEL: 050997 FRAME: 0105

COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)

DECLARATION

	matical an and its or a interest in			
As a below-named inventor, I hereby deck	re that this declaration is directed to the	application attached hereto,		
or to United States Application Number or	PCT International Application Number			
filed on	(if applicab	ile), entitled:		
	WITH CONTROLLABLE CHANNEL CTURING METHOD THEREOF	LENGTH AND		
The above-identified application was made	or authorized to be made by me.			
I believe I am the original inventor or an original joint inventor of a claimed invention in the above-identified application.				
I hereby acknowledge that any willful false 1001 by fine or imprisonment of not more		nishable under 18 USC		
I have reviewed and understand the conte	its of the above-identified application, in	cluding the claims.		
I am aware of the duty to disclose to the U me to be material to patentability as define material information that became available PCT international filing date of the continu	d in 37 CFR 1,56, including for centinuat between the filing date of the prior appli	ion-in-part applications,		
	ASSIGNMENT			
For valuable consideration, I, as a below-r	amed assignor, hereby assign to:			
MagnaChip Semiconductor, Ltd. 215, Daesin-ro, Heungdeok-gu Cheongju-si, Chungcheongbuk-do Republic of Korea	, 28429			
and its successors and assigns (collective	y hereinafter called "the Assignee"), the	entire right, title, and		
interest throughout the world in the inventi	ons and improvements that are the subje	ect of the application		
identified in the above declaration, which i	United States Application Number or Pr	CT International Application		
Number 16/682,439 fi	ed on November 13, 2019			
I authorize and request the attorneys apportunity and to correct any typograph	ion number and the filing date of the abo	ove-identified application		
This Assignment includes the above-ident				

This Assignment includes the above-identified application, any and all continuation applications and divisional applications claiming the benefit of the above-identified application under the United States patent laws, any and all United States and foreign patents, utility models, and design registrations granted for any of the inventions and improvements that are the subject of the above-identified application, and the right to claim priority based on the filing date of the above-identified application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, design registrations, like rights of exclusion, and inventors' certificates for any of the inventions and improvements that are the subject of the above-identified application; and I agree for myself and my heirs, legal representatives, and assigns without further compensation to perform such lawful

COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)

acts and to sign such further applications, Assignments, preliminary statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

In witness whereof, I, as a below-named inventor and assignor, intending to be legally bound, have hereunto affixed my signature on the date indicated below next to my signature.

inventor's Legal Name	Hyun Kwang SHIN	
Inventor's Signature	人きも分二	Date 2019, 11, 1
Residence (City, Country)	Cheongju-si, Republic of Korea	
Mailing Address	c/o MagnaChip Semiconductor Ltd., 215, Daesin-ro, Heungduk-gu, Cheongju-si, Chungcheongbuk-do, 28429, Republic of Korea	